

MATERIAL DECLARATION SHEET



Material Number	SF-2410FP050W~SF-2410FP200W			
Product Line	Lead Free Fast Acting Precision Wire Core Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body	Epoxy Board	38.197	Carbon	7440-44-0	41.25%	30.26%	73.35%
				Oxygen	7782-44-7	36.15%	26.51%	
				Silicon	7440-21-3	18.23%	13.37%	
				Hydrogen	1333-74-0	3.75%	2.75%	
				Aluminum	7429-90-5	0.26%	0.19%	
				Calcium	7440-70-2	0.36%	0.26%	
2	Fuse Link	Copper Composite Wire	0.178	Alloy	Trade secret	68.03%	0.239%	0.34%
				Copper	7440-50-8	31.97%	0.102%	
3	Copper Layer (Termination)	Copper	11.15	Copper	7440-50-8	100.00%	21.41%	21.41%
4	Nickel Layer (Termination)	Nickel	1.632	Nickel	7440-02-0	100.00%	3.13%	3.13%

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5	Tin Layer (Termination)	Tin	0.816	Tin	7440-31-5	100.00%	1.57%	1.57%
6	Marking	Marking Ink	0.105	Oxygen	7782-44-7	33.48%	0.067%	0.20%
				Carbon	7440-44-0	32.86%	0.066%	
				Titanium	7440-32-6	16.20%	0.033%	
				Barium	7440-39-3	6.08%	0.012%	
				Silicon	7440-21-3	3.77%	0.0076%	
				Hydrogen	1333-74-0	3.69%	0.0075%	
				Magnesium	7439-95-4	1.88%	0.0038%	
				Silicon	7704-34-9	1.42%	0.0029%	
				Nitrogen	7727-37-9	0.61%	0.00124%	
		Total weight	52.078					

This Document was updated on: 8-30-2017

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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Material Number	SF-2410FP250W~SF-2410FP1000W			
Product Line	Lead Free Fast Acting Precision Wire Core Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body	Epoxy Board	0.038228	Graphite	7782-42-5	41.25%	30.07%	72.75%
				Oxygen	7782-44-7	36.15%	26.26%	
				Silicon	7440-21-3	18.23%	13.24%	
				Hydrogen	1333-74-0	3.75%	2.72%	
				Aluminum	7429-90-5	0.26%	0.19%	
				Calcium	7440-70-2	0.36%	0.26%	
2	Fuse Link	Copper Composite Wire	0.00062	Copper	7440-50-8	100.00%	1.18%	1.18%
3	Copper Layer (Termination)	Copper	0.01115	Copper	7440-50-8	100.00%	21.22%	21.22%
4	Nickel Layer (Termination)	Nickel	0.00163	Nickel	7440-02-0	100.00%	3.10%	3.10%
5	Tin Layer (Termination)	Tin	0.000816	Tin	7440-31-5	100.00%	1.55%	1.55%
6	Marking	Marking Ink	0.000105047	Oxygen	7782-44-7	33.48%	0.07%	0.20%
				Graphite	7782-42-5	32.86%	0.07%	
				Titanium	7440-32-6	16.20%	0.03%	
				Barium	7440-39-3	6.08%	0.01%	
				Silicon	7440-21-3	3.77%	0.01%	

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				Hydrogen	1333-74-0	3.69%	0.01%	
				Magnesium	7439-95-4	1.88%	0.00%	
				Sulfur	7704-34-9	1.42%	0.00%	
				Nitrogen	7727-37-9	0.61%	0.00%	
			Total weight	0.052549047				

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.